CERTIFICATE OF ACCREDITATION

The ANSI National Accreditation Board

Hereby attests that

SMT Corporation
14 High Bridge Road
Sandy Hook, CT 06482

Fulfills the requirements of

ISO/IEC 17025:2017

and

AS6171 Detection of Suspect/Counterfeit Parts Accreditation Program

In the field of

TESTING

This certificate is valid only when accompanied by a current scope of accreditation document.
The current scope of accreditation can be verified at www.anab.org.

Jason Stine, Vice President

Expiry Date: 22 October 2026

Certificate Number: AT-1733

This laboratory is accredited in accordance with the recognized International Standard ISO/IEC 17025:2017. This accreditation demonstrates technical competence for a defined scope and the operation of a laboratory quality management system (refer to joint ISO-ILAC-IAF Communiqué dated April 2017).

SCOPE OF ACCREDITATION TO ISO/IEC 17025:2017

SMT Corporation

14 High Bridge Road, Sandy Hook, CT 06482
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In recognition of a successful assessment to ISO/IEC 17025:2017 General Requirements for the competence of Testing and Calibration Laboratories, AS6171 General Requirements, and the requirements of the ANAB SR 2429 – Labs Performing Detection of Suspect/Counterfeit Parts Under AS6171 program, accreditation is granted to the **SMT Corporation** to perform the following AS6171 slash sheet tests:

TESTING

Valid to: **October 22, 2026** Certificate Number: **AT-1733**

Non-Destructive Testing

Specific Tests and/or Properties Measured	Specification, Standard, Method, or Test Technique	Items, Materials or Product Tested	Key Equipment or Technology
Radiographic Examination / Inspection	Internal Procedures: W750-15 W750-34 W750-36 IDEA-STD-1010 AS6081 AS6171 AS6171/5	Electrical, Electronic and Electromechanical (EEE) Components	DAGE Quadra 5 Manual Radiography and Semi-Automatic Radiography
X-Ray Fluorescence (XRF)	Internal Procedures: W750-16 IDEA-STD-1010 AS6171 AS6171/3	Electrical, Electronic and Electromechanical (EEE) Components	Fischer XDAL Spectrometer X-Ray Fluorescence (XRF) System
Visual Inspection	Internal Procedure: W750-18 IDEA-STD-1010 AS6081 AS6171 AS6171/2	Electrical, Electronic and Electromechanical (EEE) Components	Keyence VHX-7000 Digital Microscope, Nikon D90 Camera, Dino-lite Camera

Mechanical

Specific Tests and/or Properties Measured	Specification, Standard, Method, or Test Technique	Items, Materials or Product Tested	Key Equipment or Technology
Resistance to Solvents (RTS) / Scrape Test	Internal Procedure: W750-11 W750-13 IDEA-STD-1010 AS6081 AS6171 AS6171/2	Electrical, Electronic and Electromechanical (EEE) Components	Hot Plate, X-Acto Number 11 blade, Cotton Swab, Solvents
Scanning Electron Microscopy (SEM) Examination / Inspection	Internal Procedure: W750-12 IDEA-STD-1010 AS6081 AS6171 AS6171/2	Electrical, Electronic and Electromechanical (EEE) Components	Tescan Vega Variable Pressure SEM
Packaging Configuration and Dimensions	Internal Procedure: W750-19 MIL-STD-883 Method 2016 IDEA-STD-1010 AS6081 AS6171 AS6171/2	Electrical, Electronic and Electromechanical (EEE) Components	Calipers Device to print Package Dimensions Non-Contact Measurement Tool
Solderability Test	Internal Procedures: W750-14 IDEA-STD-1010 J-STD-002 MIL-STD-883 MIL-STD-202 IEC 60068-2-20	Electrical, Electronic and Electromechanical (EEE) Components	GEN3 MUST3 Automated Force Wetting Solderability System
Dynasolve / 1-Methyl 2- Pyrrolidinone	Internal Procedure: W750-09 IDEA-STD-1010 AS6081 AS6171 AS6171/2	Electrical, Electronic and Electromechanical (EEE) Components	Hot Plate, X-Acto Number 11 blade, Cotton Swab, Solvents
Decapsulation and Die Verification	Internal Procedure: W750-10 W750-21 IDEA-STD-1010 AS6081 AS6171 AS6171/4	Electrical, Electronic and Electromechanical (EEE) Components	Nisene Jet-Etch Acid Decapsulator

Electrical

Specific Tests and/or Properties Measured	Specification, Standard, Method, or Test Technique	Items, Materials or Product Tested	Key Equipment or Technology
Capacitance Measurement, Contact Resistance	MIL-STD-202 METHOD: 305A, 307 Internal Procedure: W750-03, W750-02 AS6171/7	Electrical, Electronic and Electromechanical (EEE) Components	LCR Meter – Quadtech 7600B Multimeter
Forward Voltage Drop, Reverse Current Leakage, Regulator (breakdown) Voltage	MIL-STD-750 METHOD: 4011, 4016, 4022 Internal procedure: W750-4011.4, 4016.4, 4022 AS6171/7	Diodes, Zener Diodes	PXI-4130 Source-Measure Unit, PXI-4072 DMM, PXIe-6556 Digital Waveform Generator
Propagation Delay, Power Supply Current	MIL-STD-883 METHOD: 3003, 3005 Internal procedure: W883-3003, 3005 AS6171/7	Microcircuits	PXI-4130 Source-Measure Unit, PXI-4072 DMM, PXI-4110 Power Supply, PXI-6556 Digital Waveform Generator, LeCroy WavePro 7300A 3GHz Oscilloscope,
High Level Output Voltage, Low Level Output Voltage, Input Clamp Voltage	MIL-STD-883 METHOD: 3006, 3007,3022 Internal procedure: W883-3006, 3007, 3022 AS6171/7	Microcircuits	PXI-4130 Source-Measure Unit PXI-4110 Power Supply PXI-4072 DMM
Low Level Input Current, High Level Input current, Output Short Circuit Current	MIL-STD-883 METHOD: 3009, 3010, 3011 Internal procedure: W883-3009, 3010, 3011	Microcircuits	PXI-4130 Source-Measure Unit PXI-4110 Power Supply PXI-4072 DMM
Functional Testing	MIL-STD-883 METHOD 3014, Internal procedure: W883-3014	Microcircuits	PXI-4110 Power Supply PXI-6556 Digital Waveform Generator

Note:

1. This scope is formatted as part of a single document including Certificate of Accreditation No. AT-1733.

Jason Stine, Vice President